AN8488SB

3-phase full-wave motor driver and DC motor BTL driver IC

■ Overview

The AN8488SB is a motor driver IC incorporating a 3-phase full-wave motor driver and DC motor BTL driver IC with a reverse rotation brake/short brake changeover function. It is encapsulated into a high allowable power dissipation package (with copper block).

■ Features

- 3-phase full-wave and snubberless
- FG output
- Current limit
- Reverse rotation prevention
- Thermal protection circuit built-in

■ Applications

• Various types of optical disk drive

Pin No. | Symbol | Description 19 H2− Hall element-2 negative input pin 20 | H3+ | Hall element-3 positive input pin 21 H3− Hall element-3 negative input pin 22 \vert V_{CC1} \vert SPD block supply voltage pin 23 | VH | Hall bias pin 24 | N.C. | N.C. 25 | SS | Start/stop changeover pin 26 | ECR | Torque command reference input pin 27 | EC | Torque command input pin 28 | PCI | Current feedback phase compensation pin 29 | VM1 | SPD block motor supply voltage pin 30 | N.C. | N.C. 31 N.C. N.C. 32 A3 A3 phase output pin 33 | N.C. | N.C. 34 | CS | Current det. pin 35 | A2 | A2 phase output pin 36 | A1 | A1 phase output pin FIN2 Pin No. | Symbol | Description 1 | PG1 | SPD block power GND pin 2 | PG2 | Driver block power GND pin 3 | N.C. | N.C. 4 VN Driver block inverted output pin 5 PC Driver block power cut pin 6 | N.C. | N.C. 7 | VP | Driver block forward output pin 8 | N.C. | N.C. 9 | VM2 | Driver block motor power supply pin 10 \vert V_{CC2} \vert Driver block supply voltage pin 11 | SLIN | Driver block input pin 12 V_{REF} Driver block reference input pin 13 | N.C. | N.C. 14 | FG | FG signal output pin 15 | BRK | Brake mode setting pin 16 | H1+ | Hall element-1 positive input pin 17 H1− Hall element-1 negative input pin 18 | H2+ | Hall element-2 positive input pin FIN1 \parallel SG \parallel Signal GND pin

■ Pin Descriptions

■ Absolute Maximum Ratings

Note) Do not apply external currents or voltages to any pins not specifically mentioned.

For circuit currents, '+' denotes current flowing into the IC, and '−' denotes current flowing out of the IC.

*1: Except for the operating ambient temperature and storage temperature, all ratings are for $T_a = 25^{\circ}C$.

*2: The power dissipation shown is the value of independent IC without a heat sink at $T_a = 75^{\circ}C$. Refer to the $P_D - T_a$ curves of the "■ Application Notes" for details.

■ Absolute Maximum Ratings (continued)

Note) *3: n = 4, 7, 32, 35, 36 $*4: n = 32, 35, 36$ $*5: n = 4, 7$ $*6: n = 5, 11, 12, 15, 25, 26, 27$

■ Recommended Operating Range

Electrical Characteristics at T_a = 25°C

Electrical Characteristics at T_a = 25 $^{\circ}$ C (continued)

• Design reference data

Note) The characteristics listed below are theoretical values based on the IC design and are not guaranteed.

■ Usage Notes

- 1. Use the V_{CC2} at $V_{CC2} \ge V_{M2}$. And use power supply always at on state. Otherwise it will cause malfunction.
- 2. On driver gain setting of driver block. Voltage gain of power amplifier: 23 dB 10 kΩ

3. On operation mode of mute:

4. On SS pin mode:

5. On brake mode of spindle block:

6. Take time to check the characteristics on use. When changing an external circuit constant for use, consider not only static characteristics, but also transient characteristics and external parts with respect to the characteristics difference among ICs so that you can get enough margin.

- 7. Avoid short-circuit between output pin and power supply, output pin and GND (line-to-supply and line-to-ground fault) and output pins (load short-circuit). Otherwise the IC will be damaged and is likely to get fired.
- 8. Be cautious on a dip soldering. Prior study is required.

■ Application Notes

 \bullet P_D — T_a curves of HSOP042-P-0400

• Phase conditions between Hall input and output current

■ Application Notes (continued)

• Power consumption calculation method

You can find a rough value of electric power to be consumed in the IC in the following method and the use of EXCEL (computer soft ware) will enable you to put it on a graph.

Calculating formula:

(Spindle block)

1. Let an induced voltage generated in each phase as below:

(Reference to a motor center point)

 $E_{A1} = E_0 \times \sin (X) \cdots (1)$ $E_{A2} = E_0 \times \sin (X + 120) \cdots (2)$ $E_{A3} = E_0 \times \sin (X + 240) \cdots (3)$ X: Phase angle

2. Let a current flowing in each phase as below:

 $I_{A1} = I_0 \times \sin (X) \cdot \cdot \cdot (4)$ $I_{A2} = I_0 \times \sin (X + 120) \cdot \cdot \cdot (5)$ $I_{A3} = I_0 \times \sin (X + 240) \cdots (6)$

3. The voltages generated by a wire-wound resistance of a motor are:

$$
V_{R1} = I_{A1} \times R \cdots (7) \qquad V_{R2} = I_{A2} \times R \cdots (8) \qquad V_{R3} = I_{A3} \times R \cdots (9)
$$

4. In each phase, add the voltage generated by an induced voltage and that by a wire-wound resistance.

$$
V_{A1}' = (1) + (4) \qquad V_{A2}' = (2) + (5) \qquad V_{A3}' = (3) + (6)
$$

5. As the lowest voltage in each phase angle must be 0 V, you can get the voltage to be generated in each phase by means of subtracting the lowest voltage from the voltage of the remaining two phases.

 $V_{A1} = V_{A1}' - MIN (V_{A1}', V_{A2}', V_{A3}') \cdots (10)$ $V_{A2} = V_{A2} - MIN (V_{A1}, V_{A2}, V_{A3}) \cdots (11)$ $V_{A3} = V_{A3} - MIN (V_{A1}, V_{A2}, V_{A3}) \cdots (12)$

6. Subtract the supply voltage from each phase's voltage found in item 5 and then multiply it by each phase's current, so that you can get the power consumption of the spindle block.

$$
P_{SPD} = \sum_{n=1}^{3} (12 - V_{An}) \times I_{An}
$$

(Driver block)

 $P_{\text{SL}} = (V_{\text{M2}} - I_{\text{O}} \cdot R) \times I_{\text{O}}$ V_{M2} : Motor power supply voltage I_{Q} : Output current R: Wire wound resistor

• Theory of thermal resistance

A chip temperature or the fin temperature can be understood in the same way as Ohm's Law.

$$
T_j
$$
\n
$$
R_f
$$
\n
$$
\begin{array}{c}\n\begin{array}{c}\n\overline{T_j} : \text{ Chip temperature} \\
\overline{X_{a}} : \text{Ambient temperature} \\
\end{array} \\
\begin{array}{c}\n\overline{T_a} : \text{Ambient temperature} \\
\overline{R_{f_c}} : \text{Thermal resistance between a chip and a package} \\
\end{array} \\
\begin{array}{c}\nR_f \leq R_{c-a} \\
\overline{R_{c-a}} : \text{Thermal resistance between a package and a surface of a heat sink or free air} \\
\end{array} \\
\begin{array}{c}\nT_a \\
\overline{T_a} \\
\end{array}
$$

Make sure that T_i does not exceed 150 $^{\circ}$ C.

If it exceeds 150°C, you can suppress the rise of a chip temperature by adding a heat sink which is equivalent to R_f in the above figure.

 $T_i = T_a + P \times (R_{i-c} + R_{c-a})$

A package surface and the fin are available for a temperature measurement. But the fin part is recommendable for measurement because a package surface measurement does not always promise you a consistent measuring result.

Note) What has been mentioned above is true to a stationary state, not to a transient state.

Panasonic

■ Application Circuit Example

